

EXHIBIT 18

Exhibit 18: Exemplary Evidence of Infringement of U.S. Patent No. 11,716,816 by Apple M1 Products

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Each of the below-listed Accused Products comprises an Apple M1 processor, which infringes in accordance with the claim charts below.

Accused Products
MacBook Air (2020) Mac Mini (2020) MacBook Pro (13-inch, 2020) iMac (24-inch, 2021) iPad Pro (11-inch, 3 rd generation) iPad Pro (12.9-inch, 5 th generation) iPad Air (5 th generation)

	Claim 1	Apple M1
1 pre	1. An electronic module, comprising:	The Apple M1 comprises an electronic module.  

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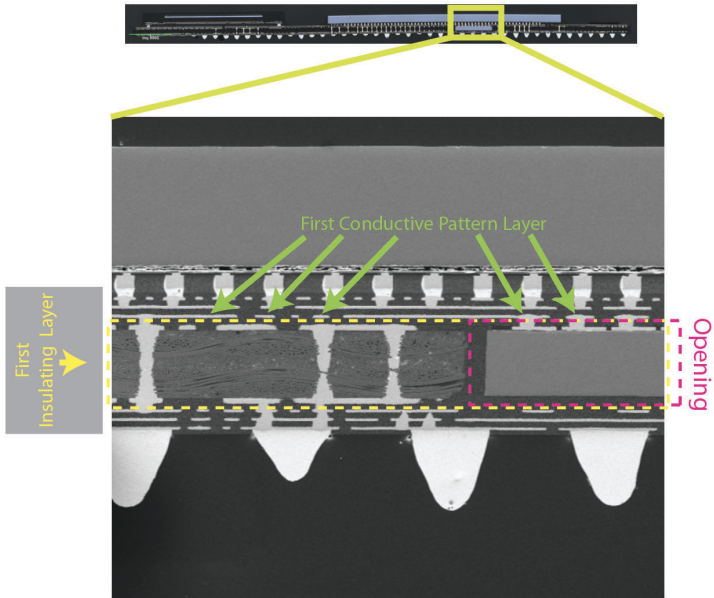
	Claim 1	Apple M1
		Electronic module cross-section
1a	a first conductive pattern layer, and a first insulating-material layer arranged on at least one surface of the first conductive pattern layer;	The Apple M1 comprises a first conductive pattern layer, and a first insulating-material layer arranged on at least one surface of the first conductive pattern layer. 
1b	at least one opening in the first insulating-material layer that extends through the first insulating-material layer;	The Apple M1 comprises at least one opening in the first insulating-material layer that extends through the first insulating-material layer.

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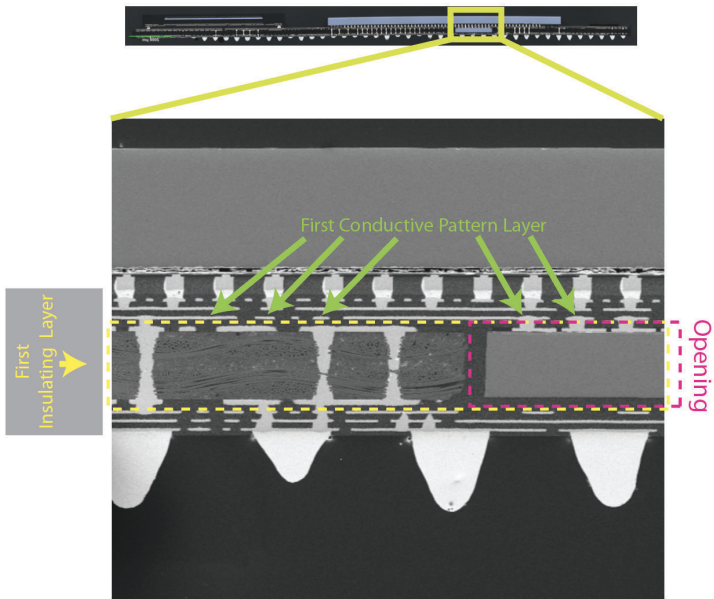
	Claim 1	Apple M1
		 The micrograph shows a cross-section of a component. At the top, a yellow box highlights a specific area. Below this, a series of contact terminals are visible. A green arrow points to the 'First Conductive Pattern Layer' which is situated above the contact terminals. A yellow dashed line indicates the 'First Insulating Layer' below the conductive pattern. A pink dashed line outlines an 'Opening' in the insulating layer. The bottom of the image shows a series of rounded, protruding structures.
1c	a component comprising contact terminals, the component being arranged at least partially within the at least one opening, the contact terminals electrically connected to the first conductive pattern layer;	The Apple M1 comprises a component, for example a semiconductor capacitor, comprising contact terminals, the component being arranged at least partially within the at least one opening, the contact terminals electrically connected to the first conductive pattern layer.

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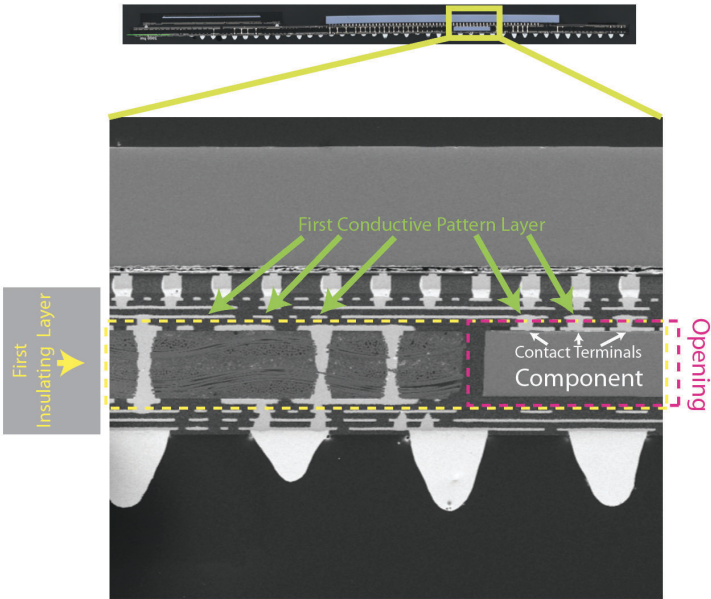
	Claim 1	Apple M1
		 The contact terminals are electrically connected to the first conductive pattern layer by metallization comprising copper.

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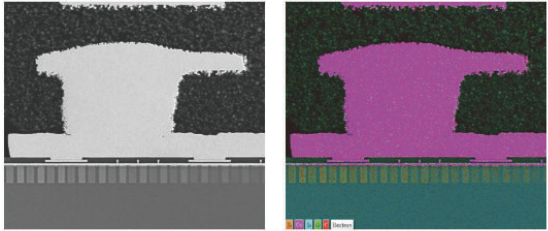
	Claim 1	Apple M1
		
1 d	a second insulating-material layer disposed on the first insulating-material layer; and	The Apple M1 comprises a second insulating-material layer disposed on the first insulating-material layer.

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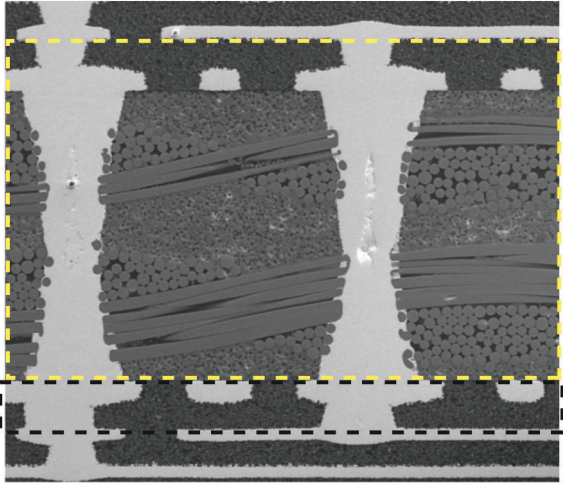
	Claim 1	Apple M1
		First Insulating Layer → → Second Insulating Layer 

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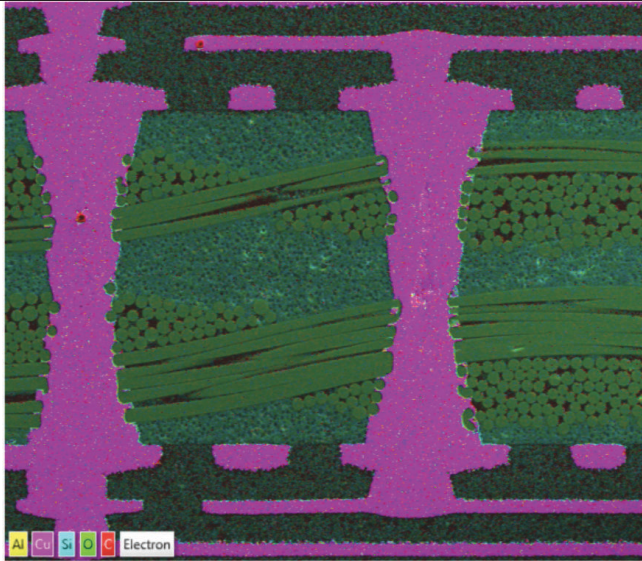
	Claim 1	Apple M1
		
1 e	a second conductive pattern layer spaced apart from the first conductive pattern layer by at least the first and second insulating-material layers,	The Apple M1 comprises a second conductive pattern spaced apart from the first conductive pattern layer by at least the first and second insulating-material layers.

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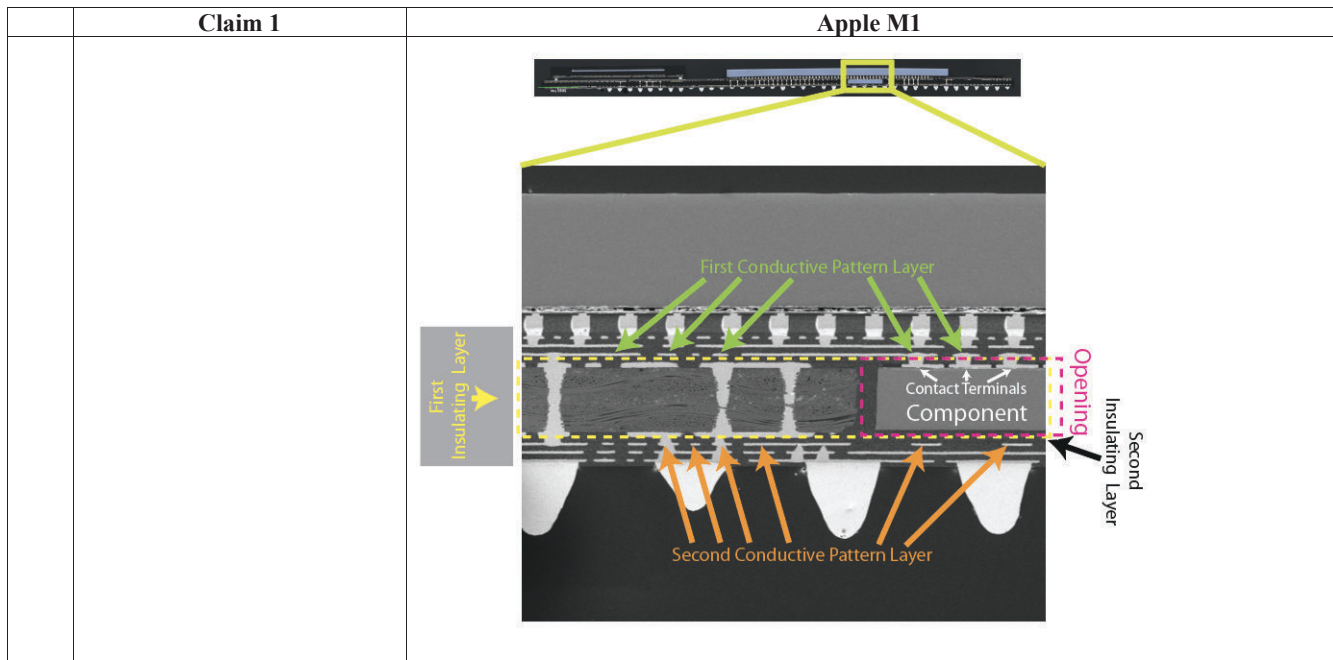
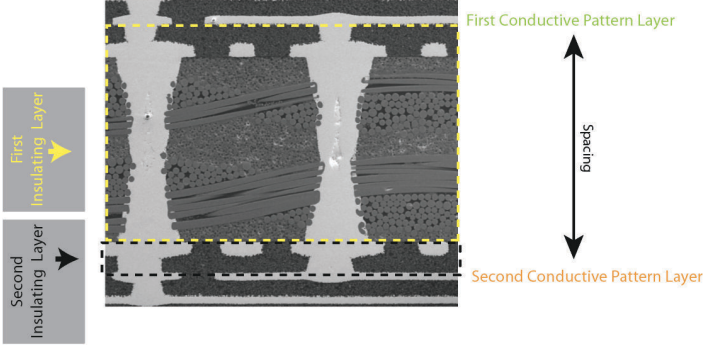


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	Claim 1	Apple M1
		
1f	wherein the first conductive pattern layer and the second conductive pattern layer are each substantially planar.	In the Apple M1, the first conductive pattern layer and the second conductive pattern layer are each substantially planar. 